

27th Annual Components for Military and Space Electronics Conference and Exhibition

April 30 - May 2, 2024

Four Points by Sheraton (LAX)
Los Angeles, California



Call for Presentations

The premier event focused on the design, reliability, and application of microelectronic components for use in both terrestrial applications for avionics, aerospace, and military, as well as commercial, civilian, and military space systems. Three days of technical talks and cutting edge tutorials taught by industry professionals.

We request presentation outlines at CMSE 2024 on topics such as:

- Integration of next gen 2.5/3D FOWL packaging into mil systems
- Non-Hermetics: Class P, Class Y and COTS for Hi Rel missions
- Leveraging automotive parts for military and space
- Selection and approval process for PEMS/COTS
- Hermetics: IGA (TM 1018) moisture issues, TM 1014 testing and getters
- EEE parts engineering issues for small satellites
- PME/BME MLCCs and MIL-PRF stacked caps
- Supercapacitors and high CV for high rel applications
- Transient response of passive components
- Ultra-thin embedded passives to enable circuit miniaturization
- Tantalum polymer progression towards space and wear out
- GaN and SiC for RF and power management
- AI tools and digital engineering/model-based design
- Continuity of the electronics supply chain
- Counterfeits, trust, and security issues in supply chain management
- Long term dormant storage (Hermetic vs. Non-Hermetic)
- CHIPS for America act securing our DOD Industrial base

Presentations are 15 minutes with 5 minutes of Q & A. The CMSE committee does not require a formal paper submission. You decide how much of the presentation material to provide the attendee. The idea is to promote sharing of basic scientific and technical information about common problems faced by both the component manufacturer and the system OEMs in the Aerospace industry.

Please email your presentation outline to: info@tjgreenllc.com

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